Application No.:

10/676,895

Filing Date:

September 20, 2003

AMENDMENTS TO THE CLAIMS

Claims 1-14 were pending prior to the entry of these amendments. Please cancel Claims 1-8 without prejudice or disclaimer. Please amend Claim 9 as indicated below.

- 1. (Canceled)
- 2. (Canceled)
- 3. (Canceled)
- 4. (Canceled)
- 5. (Canceled)
- 6. (Canceled)
- 7. (Canceled)
- 8. (Canceled)
- 9. (**Currently Amended**) An edge copper removal system for removing conductive material from an edge region of a workpiece subsequent to an electrochemical process as the workpiece rotated, wherein the edge region comprises a front edge surface, a back edge surface, and a bevel, the system comprising:

at least one nozzle for directing a first etchant flow onto the back edge surface of the workpiece; <u>and</u>

at least one other nozzle for directing a second etchant flow onto the front surface edge of the workpiece.

- 10. (Original) The system of Claim 9, wherein the at least one nozzle and the at least one other nozzle receive etchant from the same etchant supply tank.
- 11. (Original) The system of Claim 9, wherein the at least one nozzle and the at least one other nozzle receive etchant from different etchant supply tanks.
- 12. (Original) The system of Claim 9, wherein the at least one nozzle and the at least one other nozzle are integral parts of an edge copper removal device.
- 13. (Original) The system of Claim 9, wherein a flow rate of the first etchant flow is different than a flow rate of the second etchant flow.
- 14. (Original) The system of Claim 9, wherein a flow rate of the first etchant flow is the same as a flow rate of the second etchant flow.